

SE138U
N-Channel Enhancement-Mode MOSFET

Revision: B

General Description

Thigh Density Cell Design For Ultra Low On-Resistance Fully Characterized Avalanche Voltage and Current Improved Shoot-Through FOM

- Simple Drive Requirement
- Small Package Outline
- Surface Mount Device

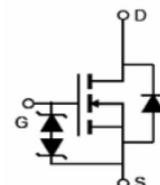
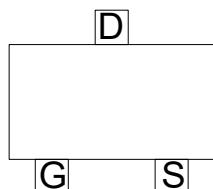
Features

For a single MOSFET

- $V_{DS} = 60V$
- $R_{DS(ON)} = 0.7\Omega @ V_{GS}=10V$

Pin configurations

See Diagram below



SOT-323

Absolute Maximum Ratings

| Parameter | Symbol | Rating | Units |
|--------------------------------------|---------------------|------------|-------|
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current | Continuous | I_D | A |
| | Pulsed ¹ | | |
| Total Power Dissipation @TA=25°C | P_D | 0.36 | W |
| Operating Junction Temperature Range | T_J | -55 to 150 | °C |

Thermal Resistance

| Symbol | Parameter | Typ | Max | Units |
|-----------------|--|-----|-----|-------|
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient | - | 350 | °C/W |

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| Electrical Characteristics (TJ=25°C unless otherwise noted) | | | | | | |
|---|-----------------------------------|--|-----|-----|------|-------|
| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
| OFF CHARACTERISTICS (Note 2) | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | I _D =250μA, V _{GS} =0 V | 60 | | | V |
| I _{DSS} | Drain to Source Leakage Current | V _{DS} = 30V, V _{GS} =0V | | | 100 | nA |
| I _{GSS} | Gate-Body Leakage Current | V _{GS} =20V | | | 100 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D =1mA | 0.8 | 1.3 | 1.5 | V |
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =10V, I _D =0.22A | - | 0.7 | 1.6 | Ω |
| | | V _{GS} =4.5V, I _D =0.22A | | 1.0 | 3.6 | |
| DYNAMIC PARAMETERS | | | | | | |
| C _{iss} | Input Capacitance | V _{GS} =0V, V _{DS} =25V, f=1MHz | | 27 | | pF |
| C _{oss} | Output Capacitance | | | 13 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 6 | | pF |
| SWITCHING PARAMETERS | | | | | | |
| Q _g | Total Gate Charge | V _{GS} =10V, V _{DS} =25V, I _D =0.22A | | 1.7 | 2.4 | nC |
| Q _{gs} | Gate Source Charge | | | 0.1 | | nC |
| Q _{gd} | Gate Drain Charge | | | 0.4 | | nC |
| t _{d(on)} | Turn-On Delay Time | V _{GS} =10V, V _{DS} =30V, R _{GEN} =6Ω, I _D =0.29A | | 2.5 | 5 | ns |
| t _{d(off)} | Turn-Off Delay Time | | | 20 | 36 | ns |
| t _{d(r)} | Turn-On Rise Time | | | 9 | 18 | ns |
| t _{d(f)} | Turn-Off Fall Time | | | 7 | 14 | ns |
| Source-Drain Diode | | | | | | |
| Symbol | Parameter | Test Condition | Min | Typ | Max | Units |
| I _S | Source Current | I _F =0.44A, V _{DS} =0V, dI/dt=100A/μs | | | 0.22 | A |
| V _{SD} | Diode Forward Voltage | | | 0.8 | 1.4 | V |

Typical Characteristics

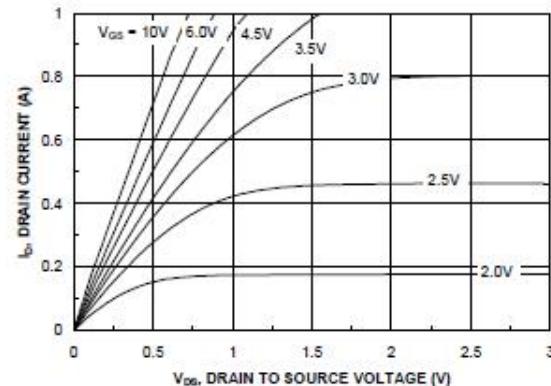


Figure 1. On-Region Characteristics.

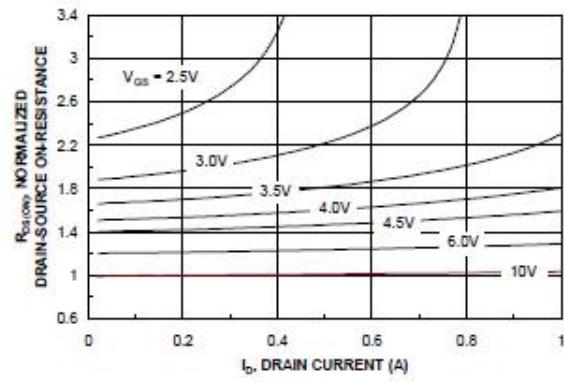


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

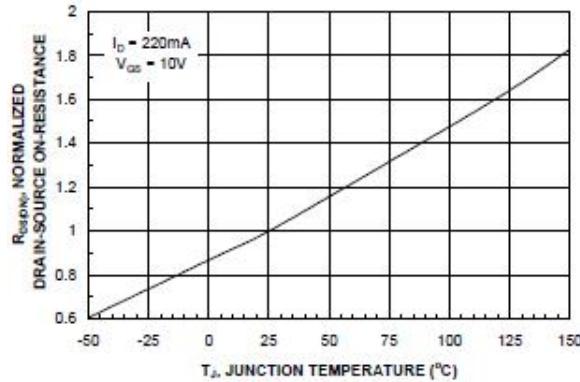


Figure 3. On-Resistance Variation with Temperature.

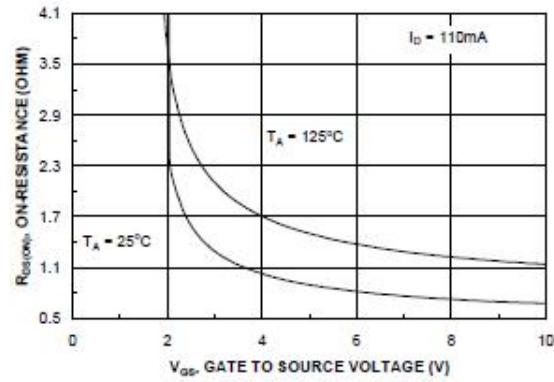


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

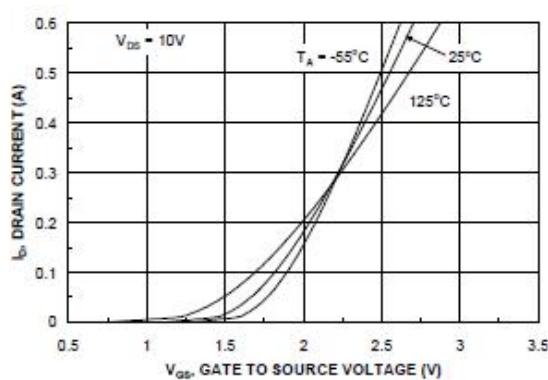


Figure 5. Transfer Characteristics.

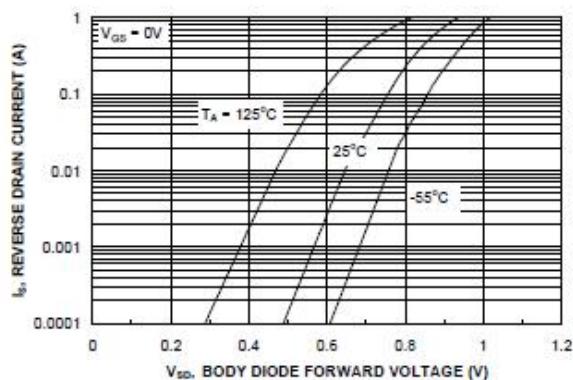


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

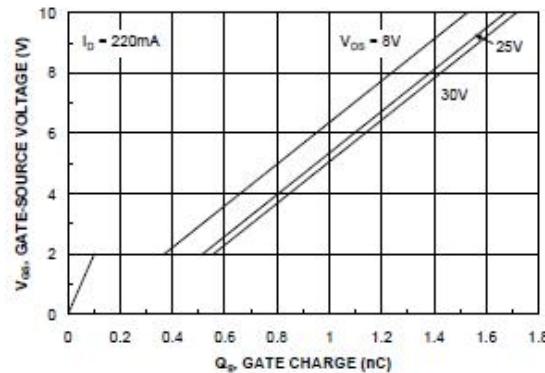


Figure 7. Gate Charge Characteristics.

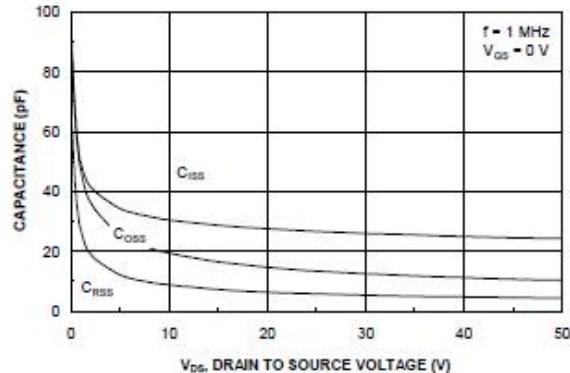


Figure 8. Capacitance Characteristics.

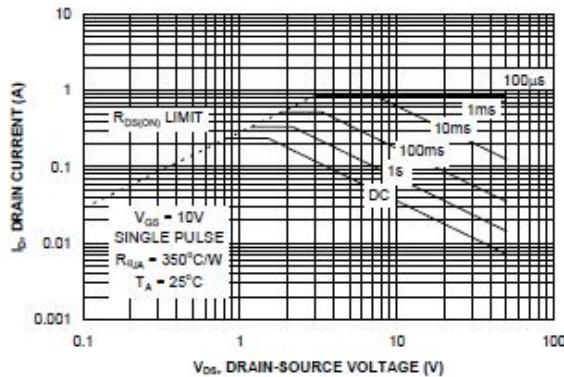


Figure 9. Maximum Safe Operating Area.

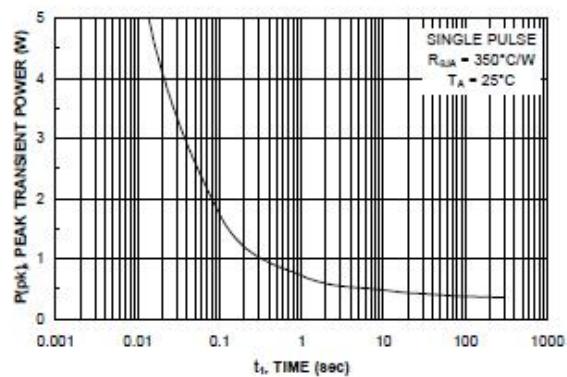


Figure 10. Single Pulse Maximum Power Dissipation.

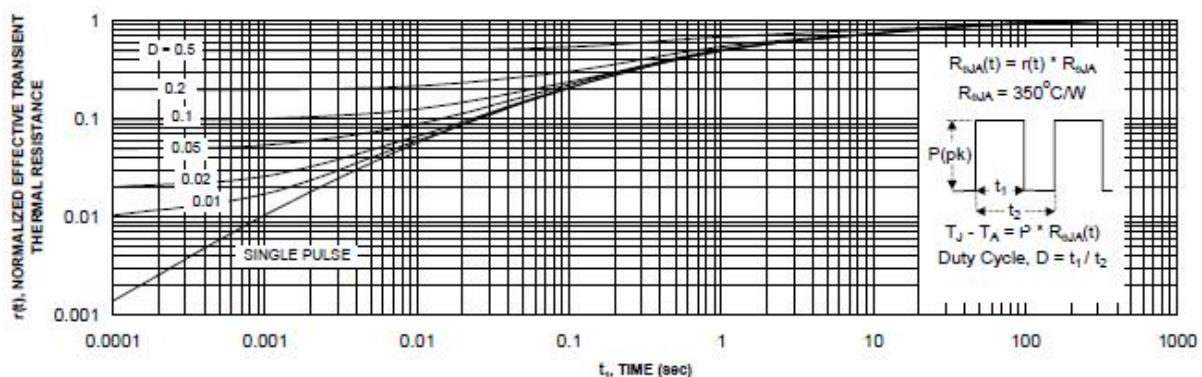
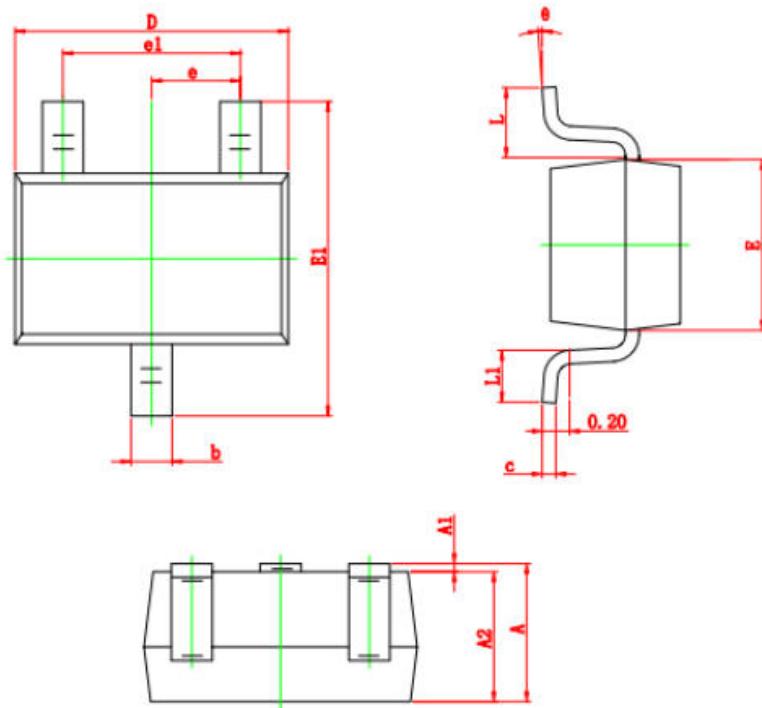


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1a.
Transient thermal response will change depending on the circuit board design.

Package Outline Dimension

SOT-323



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 0.900 | 1.100 | 0.035 | 0.043 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 0.900 | 1.000 | 0.035 | 0.039 |
| b | 0.200 | 0.400 | 0.008 | 0.016 |
| c | 0.080 | 0.150 | 0.003 | 0.006 |
| D | 2.000 | 2.200 | 0.079 | 0.087 |
| E | 1.150 | 1.350 | 0.045 | 0.053 |
| E1 | 2.150 | 2.450 | 0.085 | 0.096 |
| e | 0.650 TYP | | 0.026 TYP | |
| e1 | 1.200 | 1.400 | 0.047 | 0.055 |
| L | 0.525 REF | | 0.021 REF | |
| L1 | 0.260 | 0.460 | 0.010 | 0.018 |
| θ | 0° | 8° | 0° | 8° |

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SHANGHAI SINO-IC MICROELECTRONICS CO., LTD

Add: Building 3, Room 3401-03, No.200 Zhangheng Road, ZhangJiang Hi-Tech Park, Pudong, Shanghai 201203, China
Phone: +86-21-33932402 33932403 33932405 33933508 33933608
Fax: +86-21-33932401
Email: webmaster@sino-ic.net
Website: <http://www.sino-ic.net>

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